

MA72

Silicon epitaxial planer type

For band switching

■ Features

- Low forward dynamic resistance r_f
- Less voltage dependence of diode capacity C_D
- Mini package, enabling down-sizing of the equipment and automatic insertion through taping

■ Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	35	V
Forward current (DC)	I_F	100	mA
Operating ambient temperature	T_{opr}^*	- 25 to + 85	$^\circ\text{C}$
Storage temperature	T_{stg}	- 55 to +150	$^\circ\text{C}$

* Maximum ambient temperature during operation

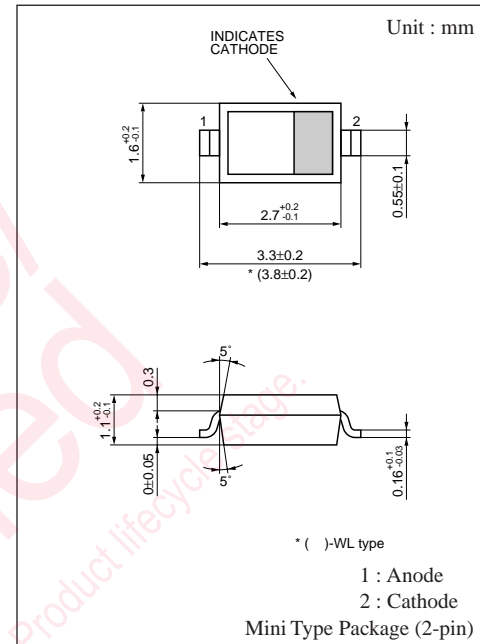
■ Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	I_R	$V_R = 33\text{V}$		0.01	100	nA
Forward voltage (DC)	V_F	$I_F = 100\text{mA}$		0.88	1	V
Diode capacitance	C_D	$V_R = 6\text{V}, f = 1\text{MHz}$		1.3	2	pF
Forward dynamic resistance	r_f^*	$I_F = 2\text{mA}, f = 100\text{MHz}$		0.78	1.15	Ω

Note 1 : Rated input/output frequency : 100MHz

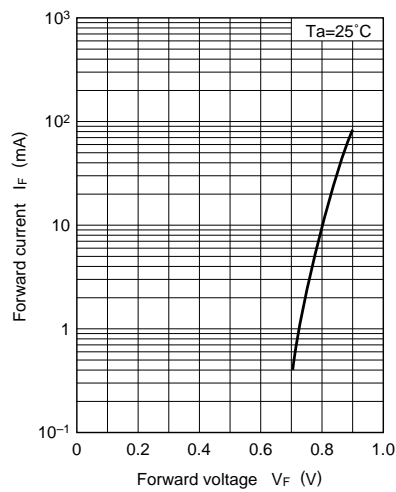
2 : * r_f measurement device : YHP MODEL 4191A RF IMPEDANCE ANALYZER

■ Marking

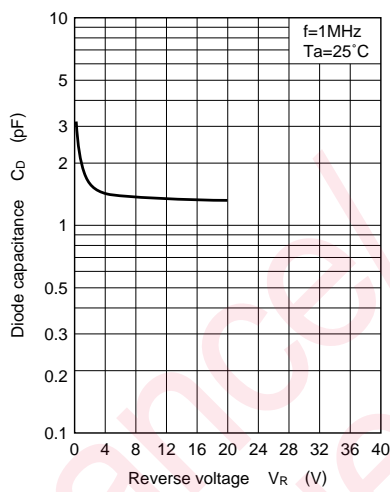


Marking Symbol : 4A

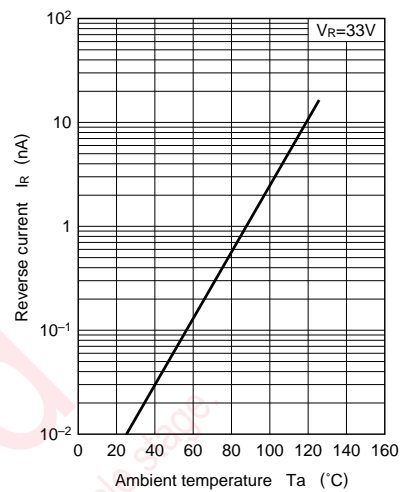
$I_F - V_F$



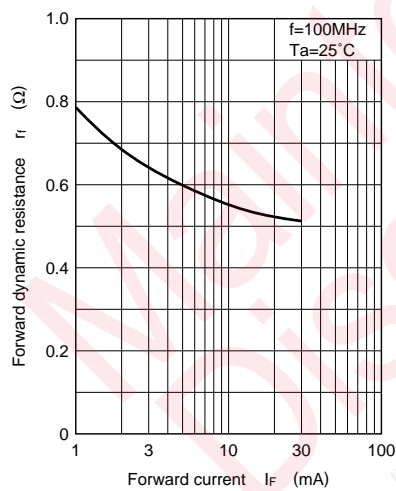
$C_D - V_R$



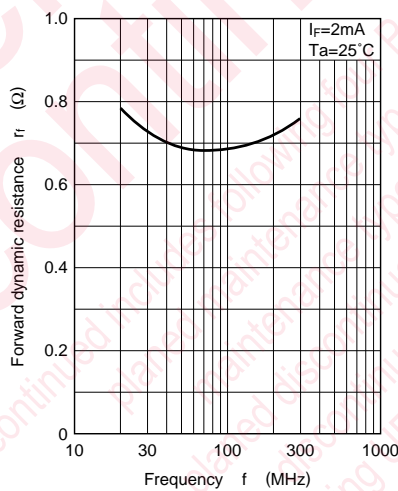
$I_R - T_a$



$r_f - I_F$



$r_f - f$



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